

# PS9332L, PS9332L2

R08DS0105EJ0100  
Rev.1.00  
Sep 06, 2013

2.0 A OUTPUT CURRENT, HIGH CMR, IGBT GATE DRIVE, ACTIVE MILLER CLAMP, 8-PIN SDIP PHOTOCOUPLER

## DESCRIPTION

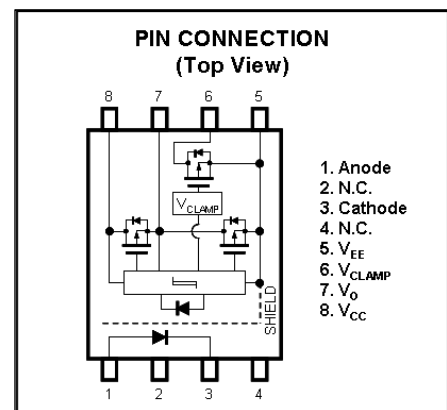
The PS9332L and PS9332L2 are optical coupled isolators containing a GaAlAs LED on the input side and a photo diode, a signal processing circuit and a power output transistor on the output side on one chip.

The PS9332L and PS9332L2 are designed specifically for high common mode transient immunity (CMR), high output current, active miller clamp and high switching speed.

The PS9332L and PS9332L2 are suitable for driving IGBTs and MOS FETs.

## FEATURES

- Long creepage distance (8 mm MIN.: PS9332L2)
- Peak output current (2.0 A MAX., 1.5 A MIN.)
- High speed switching ( $t_{PLH}$ ,  $t_{PHL}$  = 200 ns MAX.)
- UVLO (Under Voltage Lock Out) protection with hysteresis
- Built-in Active Miller Clamp
- High common mode transient immunity ( $CM_H$ ,  $CM_L$  =  $\pm 50$  kV/ $\mu$ s MIN.)
- Operating Ambient Temperature (125 °C)
- Embossed tape product : PS9332L-E3, PS9332L2-E3: 2 000 pcs/reel
- Pb-Free product
- <R> • Safety standards
  - UL approved: No. E72422
  - CSA approved: No. CA 101391 (CA5A, CAN/CSA-C22.2 60065, 60950)
  - SEMKO approved (EN 60065, EN 60950)
  - DIN EN 60747-5-5 (VDE 0884-5) approved (Option)



## APPLICATIONS

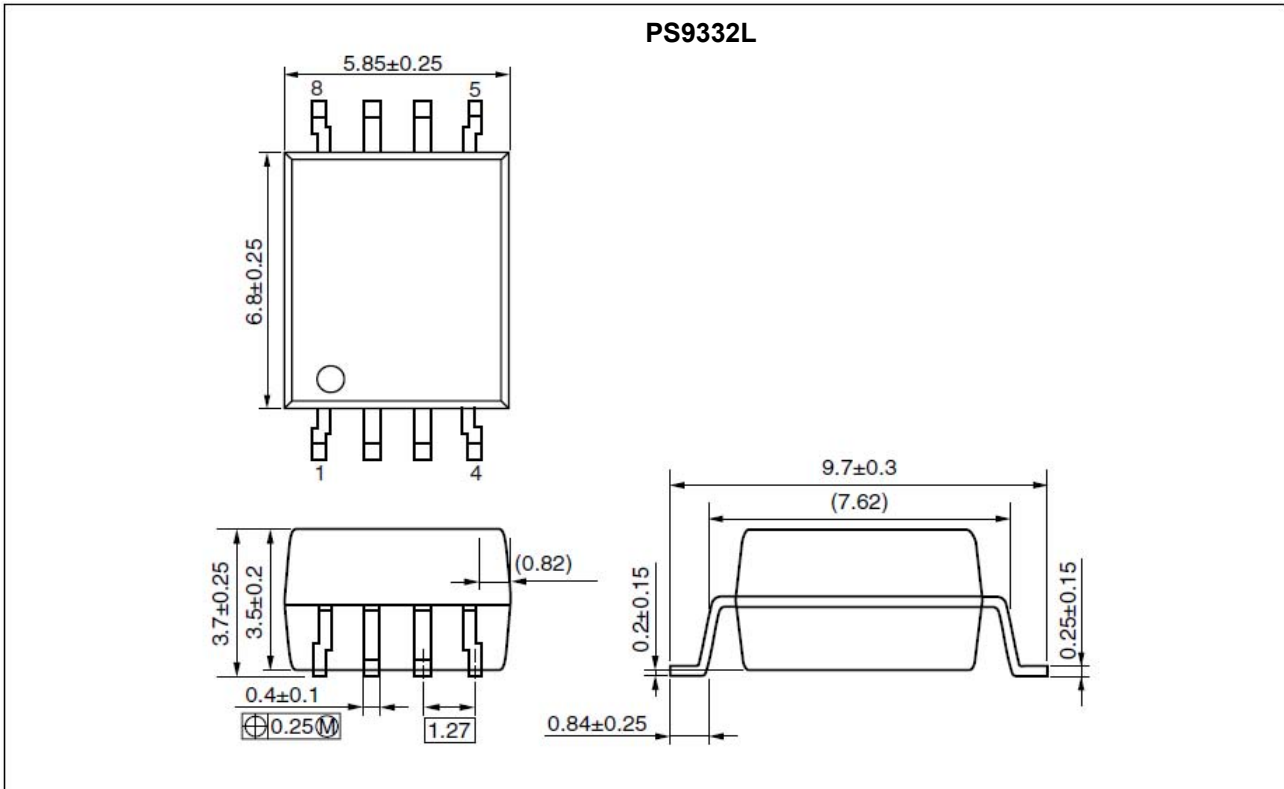
- IGBT, Power MOS FET Gate Driver
- Industrial inverter
- IH (Induction Heating)

The mark <R> shows major revised points.

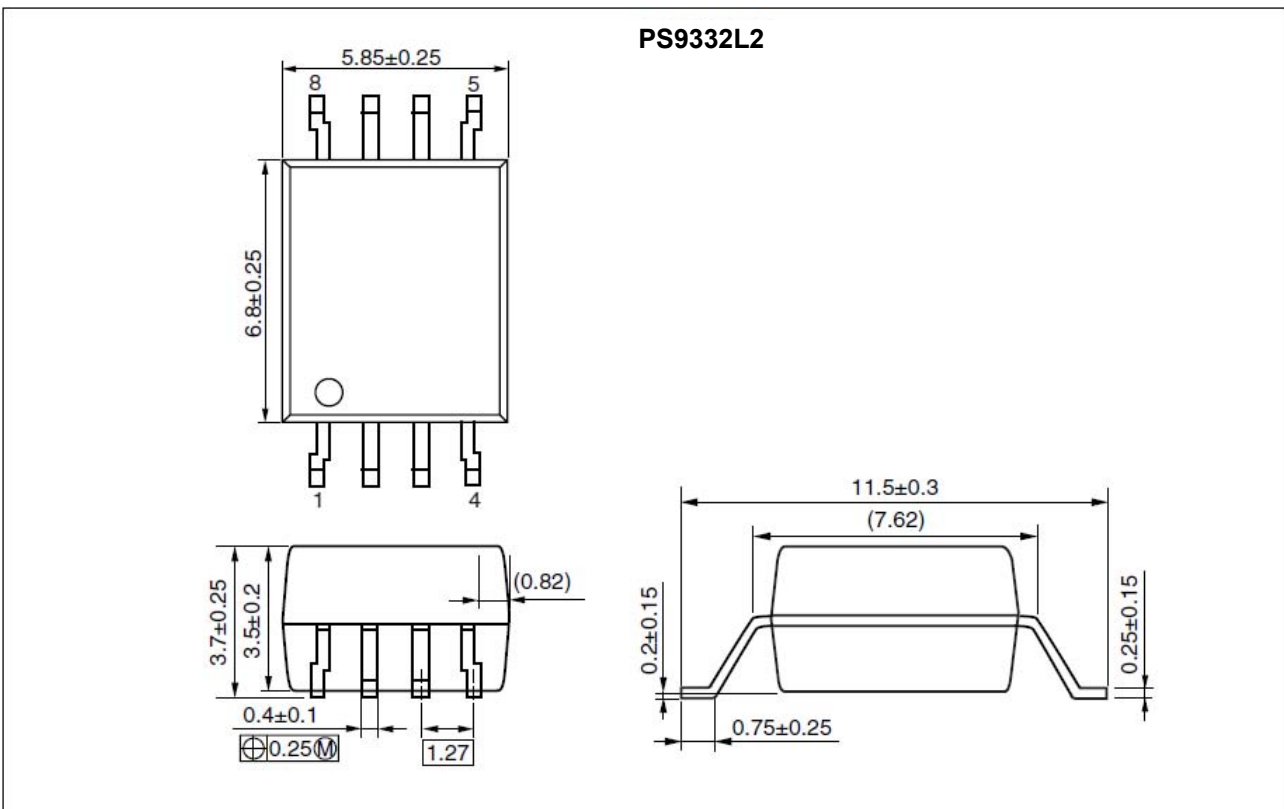
The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

**PACKAGE DIMENSIONS (UNIT: mm)**

**Lead Bending Type (Gull-wing) For Surface Mount**



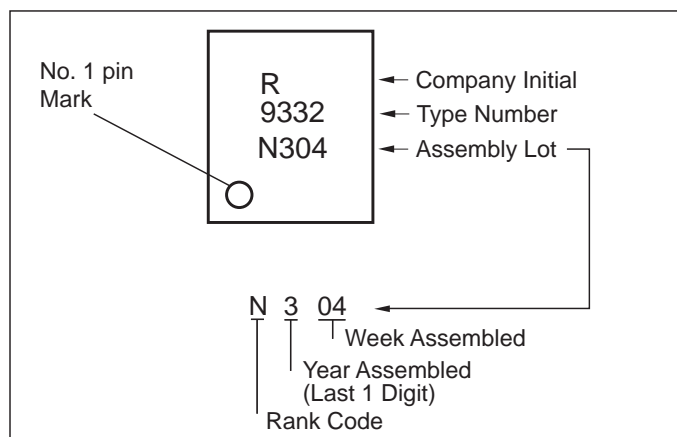
**Lead Bending Type (Gull-wing) For Long Creepage Distance (Surface Mount)**



## PHOTOCOUPLER CONSTRUCTION

Parameter	PS9332L	PS9332L2
Air Distance (MIN.)	7 mm	8 mm
Outer Creepage Distance (MIN.)	8 mm	8 mm
Isolation Distance (MIN.)	0.4 mm	0.4 mm

## MARKING EXAMPLE



## &lt;R&gt; ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number <sup>*1</sup>
PS9332L	PS9332L-AX	Pb-Free (Ni/Pd/Au)	20 pcs (Tape 20 pcs cut)	Standard products (UL, CSA,	PS9332L
PS9332L-E3	PS9332L-E3-AX		Embossed Tape 2 000 pcs/reel		
PS9332L2	PS9332L2-AX		20 pcs (Tape 20 pcs cut)	SEMKO approved)	PS9332L2
PS9332L2-E3	PS9332L2-E3-AX		Embossed Tape 2 000 pcs/reel		
PS9332L-V	PS9332L-V-AX		20 pcs (Tape 20 pcs cut)	DIN EN 60747-5-5 (VDE 0884-5) approved (Option)	PS9332L
PS9332L-V-E3	PS9332L-V-E3-AX		Embossed Tape 2 000 pcs/reel		
PS9332L2-V	PS9332L2-V-AX		20 pcs (Tape 20 pcs cut)		PS9332L2
PS9332L2-V-E3	PS9332L2-V-E3-AX		Embossed Tape 2 000 pcs/reel		

Note: \*1. For the application of the Safety Standard, following part number should be used.

<R> **ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)**

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	$I_F$	25	mA
	Peak Transient Forward Current (Pulse Width <math>< 1 \mu\text{s}</math>)	$I_{F(\text{TRAN})}$	1.0	A
	Reverse Voltage	$V_R$	5	V
	Power Dissipation <sup>*1</sup>	$P_D$	45	mW
Detector	High Level Peak Output Current <sup>*2</sup>	$I_{OH(\text{PEAK})}$	2.0	A
	Low Level Peak Output Current <sup>*2</sup>	$I_{OL(\text{PEAK})}$	2.0	A
	Supply Voltage	$(V_{CC} - V_{EE})$	0 to 35	V
	Output Voltage	$V_O$	-0.5 to $V_{CC}$	V
	Peak Clamp Sink Current	$I_{\text{CLAMP}}$	2.0	A
	Miller Clamping Pin Voltage	$V_{\text{CLAMP}}$	-0.5 to $V_{CC}$	V
	Power Dissipation <sup>*3</sup>	$P_C$	250	mW
Isolation Voltage <sup>*4</sup>		BV	5 000	Vr.m.s.
Operating Frequency <sup>*5</sup>		f	50	kHz
Operating Ambient Temperature		$T_A$	-40 to +125	$^\circ\text{C}$
Storage Temperature		$T_{\text{stg}}$	-55 to +150	$^\circ\text{C}$

Notes: \*1. Reduced to 1.1 mW/ $^\circ\text{C}$  at  $T_A = 105^\circ\text{C}$  or more.

\*2. Maximum pulse width = 10  $\mu\text{s}$ , Maximum duty cycle = 0.2%

\*3. Reduced to 5.5 mW/ $^\circ\text{C}$  at  $T_A = 105^\circ\text{C}$  or more.

\*4. AC voltage for 1 minute at  $T_A = 25^\circ\text{C}$ , RH = 60% between input and output.

Pins 1-4 shorted together, 5-8 shorted together.

\*5.  $I_{OH(\text{PEAK})} \leq 2.0 \text{ A}$  ( $\leq 0.3 \mu\text{s}$ ),  $I_{OL(\text{PEAK})} \leq 2.0 \text{ A}$  ( $\leq 0.3 \mu\text{s}$ )

**RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	$(V_{CC} - V_{EE})$	15		30	V
Forward Current (ON)	$I_{F(\text{ON})}$	7		16	mA
Forward Voltage (OFF)	$V_{F(\text{OFF})}$	-2		0.8	V
Operating Ambient Temperature	$T_A$	-40		125	$^\circ\text{C}$

<R> **ELECTRICAL CHARACTERISTICS (at RECOMMENDED OPERATING CONDITIONS,  $V_{EE} = \text{GND}$ , unless otherwise specified)**

Parameter		Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage	$V_F$	$I_F = 10 \text{ mA}$ , $T_A = 25^\circ\text{C}$	1.35	1.56	1.75	V
	Reverse Current	$I_R$	$V_R = 3 \text{ V}$ , $T_A = 25^\circ\text{C}$			10	$\mu\text{A}$
	Input Capacitance	$C_{IN}$	$f = 1 \text{ MHz}$ , $V_F = 0 \text{ V}$ , $T_A = 25^\circ\text{C}$		30		pF
Detector	High Level Output Current	$I_{OH}$	$V_O = (V_{CC} - 4 \text{ V})^{*2}$	0.5	1.5		A
			$V_O = (V_{CC} - 15 \text{ V})^{*3}$	1.5			
	Low Level Output Current	$I_{OL}$	$V_O = (V_{EE} + 2.5 \text{ V})^{*2}$	0.5	1.5		A
			$V_O = (V_{EE} + 15 \text{ V})^{*3}$	1.5			
	Clamp Output Peak Current	$I_{CLAMP}$	$V_{CLAMP} = V_{EE} + 2.5 \text{ V}$	0.5	1.6		A
	Clamp Pin Threshold Voltage	$V_{tCLAMP}$			3.0		V
	High Level Output Voltage	$V_{OH}$	$I_O = -100 \text{ mA}^{*4}$	$V_{CC} - 3.0$	$V_{CC} - 1.3$		V
	Low Level Output Voltage	$V_{OL}$	$I_O = 100 \text{ mA}$		0.1	0.5	V
	High Level Supply Current	$I_{CCH}$	$I_F = 10 \text{ mA}$ , $V_O = \text{open}$		1.5	2.5	mA
	Low Level Supply Current	$I_{CCL}$	$V_F = 0$ to $0.8 \text{ V}$ , $V_O = \text{open}$		1.5	2.5	mA
	UVLO Threshold Voltage	$V_{UVLO+}$	$V_O > 5 \text{ V}$ , $I_F = 10 \text{ mA}$	10.8	12.4	13.4	V
$V_O < 5 \text{ V}$ , $I_F = 10 \text{ mA}$			9.5	11.2	12.5		
UVLO Hysteresis	$UVLO_{HYS}$	$(V_{UVLO+}) - (V_{UVLO-})$		1.2			
Coupled	Threshold Input Current (L → H)	$I_{FLH}$	$I_O = 0 \text{ mA}$ , $V_O > 5 \text{ V}$		1.5	4.0	mA
	Threshold Input Voltage (H → L)	$V_{FHL}$	$I_O = 0 \text{ mA}$ , $V_O < 5 \text{ V}$	0.8			V

Notes: \*1. Typical values at  $T_A = 25^\circ\text{C}$ .

\*2. Maximum pulse width =  $50 \mu\text{s}$ , Maximum duty cycle = 0.5%.

\*3. Maximum pulse width =  $10 \mu\text{s}$ , Maximum duty cycle = 0.2%.

\*4.  $V_{OH}$  is measured with the DC load current in this testing. (Maximum pulse width = 2 ms, Maximum duty cycle = 20%)

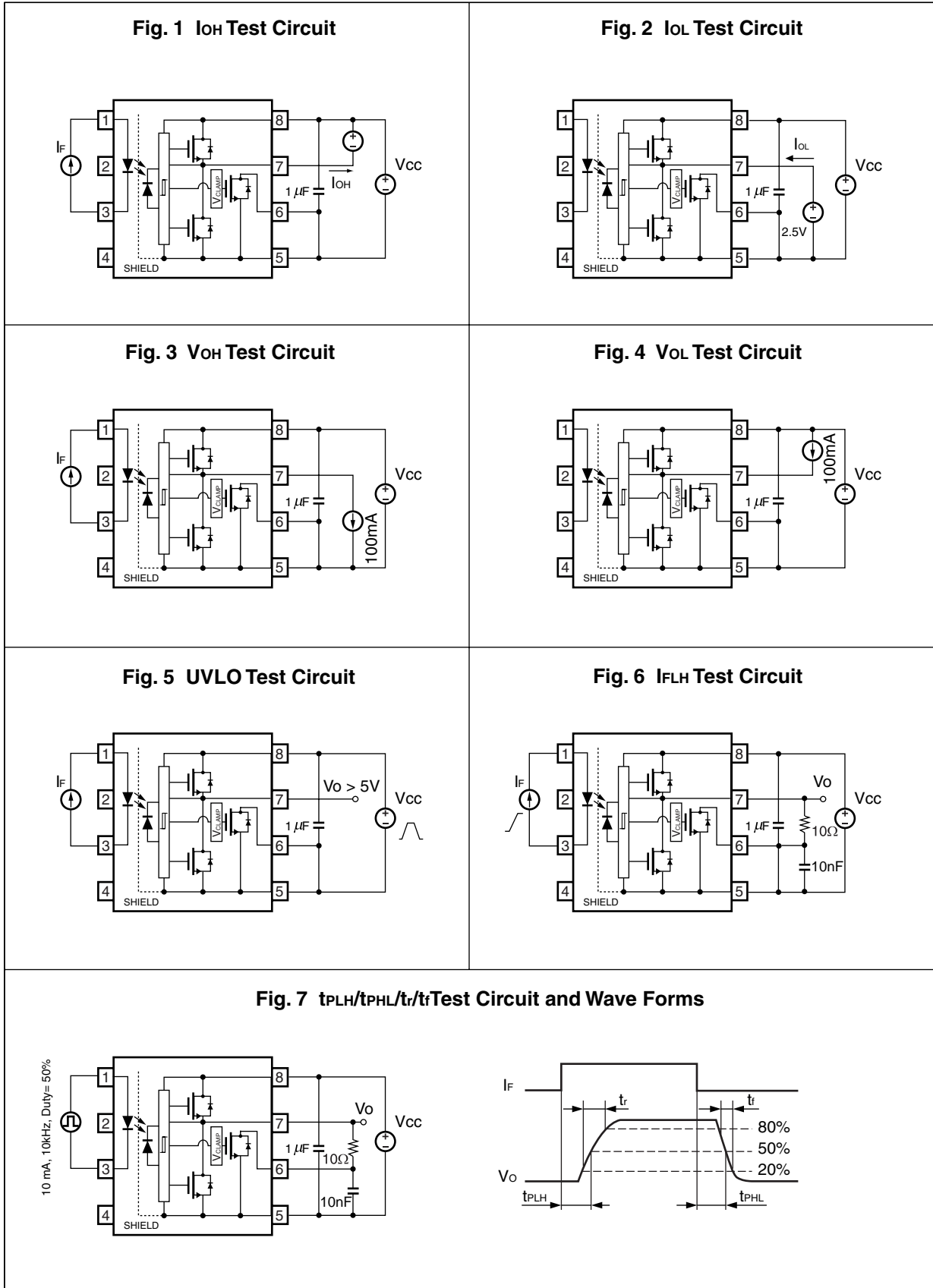
<R> **SWITCHING CHARACTERISTICS (at RECOMMENDED OPERATING CONDITIONS,  $V_{EE} = \text{GND}$ , unless otherwise specified)**

Parameter	Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit	
Propagation Delay Time (L → H)	$t_{PLH}$	$R_g = 10 \Omega$ , $C_g = 10 \text{ nF}$ , $f = 10 \text{ kHz}$ , Duty Cycle = 50%*2, $I_F = 10 \text{ mA}$		75	200	ns	
Propagation Delay Time (H → L)	$t_{PHL}$			110	200	ns	
Pulse Width Distortion (PWD)	$ t_{PHL} - t_{PLH} $				35	75	ns
Propagation Delay Time (Difference Between Any Two Products)	$t_{PHL} - t_{PLH}$			-90		90	ns
Rise Time	$t_r$				17		ns
Fall Time	$t_f$				17		ns
Common Mode Transient Immunity at High Level Output	$ CM_H $	$T_A = 25^\circ\text{C}$ , $I_F = 10 \text{ mA}$ , $V_{CC} = 30 \text{ V}$ , $V_{CM} = 1.5 \text{ kV}$ $V_{O(MIN.)} = 26 \text{ V}$	50			$\text{kV}/\mu\text{s}$	
Common Mode Transient Immunity at Low Level Output	$ CM_L $	$T_A = 25^\circ\text{C}$ , $I_F = 0 \text{ mA}$ , $V_{CC} = 30 \text{ V}$ , $V_{CM} = 1.5 \text{ kV}$ $V_{O(MAX.)} = 1 \text{ V}$	50			$\text{kV}/\mu\text{s}$	

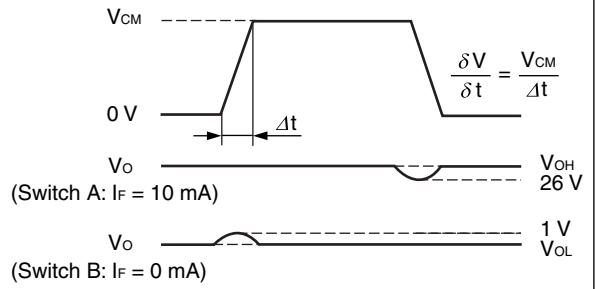
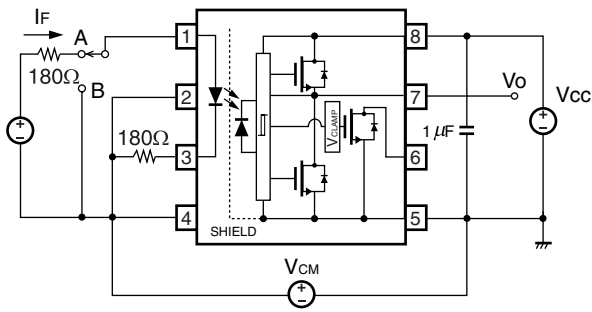
Notes: \*1. Typical values at  $T_A = 25^\circ\text{C}$ .

\*2. This load condition is equivalent to the IGBT load at 1 200 V/75 A.

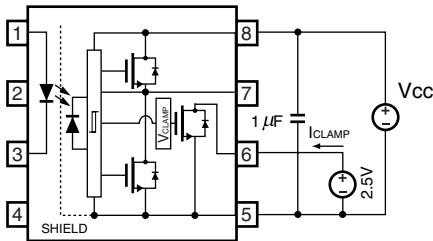
<R> TEST CIRCUIT



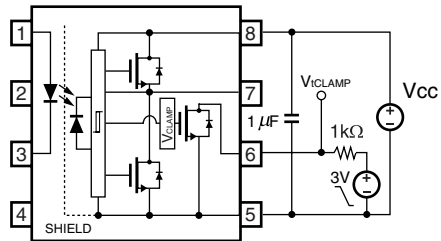
**Fig. 8 CMR Test Circuit and Wave Forms**



**Fig. 9 I<sub>CLAMP</sub> Test Circuit**

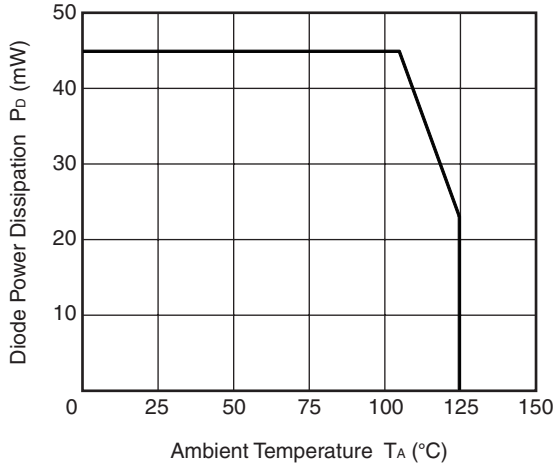


**Fig. 10 V<sub>tCLAMP</sub> Test Circuit**

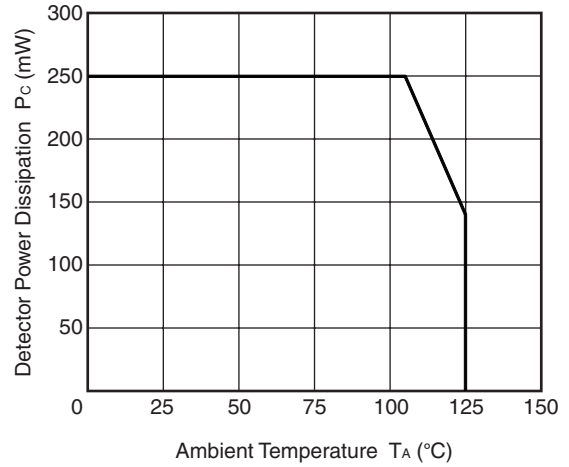


<R> **TYPICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)**

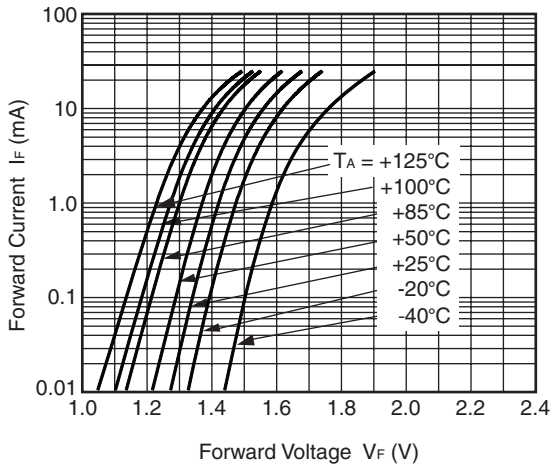
DIODE POWER DISSIPATION vs. AMBIENT TEMPERATURE



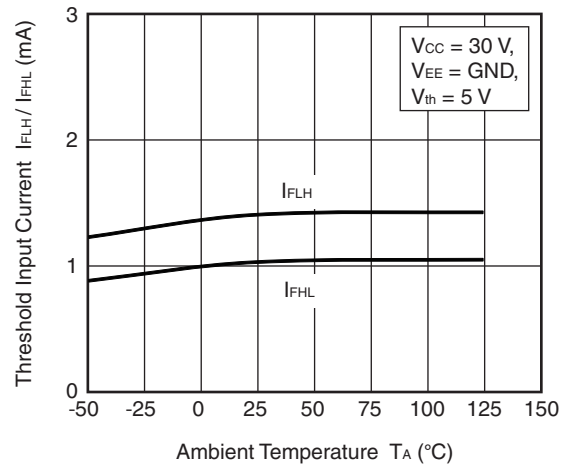
DETECTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



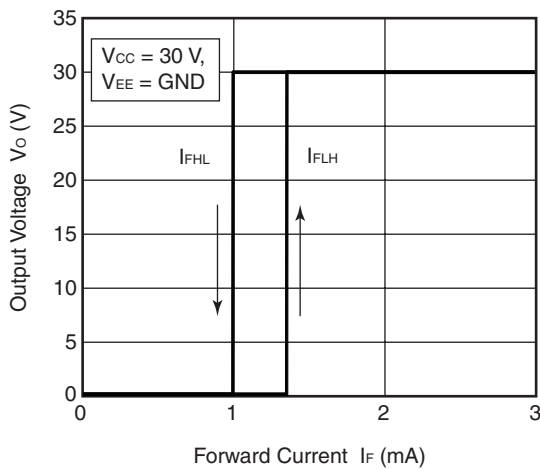
FORWARD CURRENT vs. FORWARD VOLTAGE



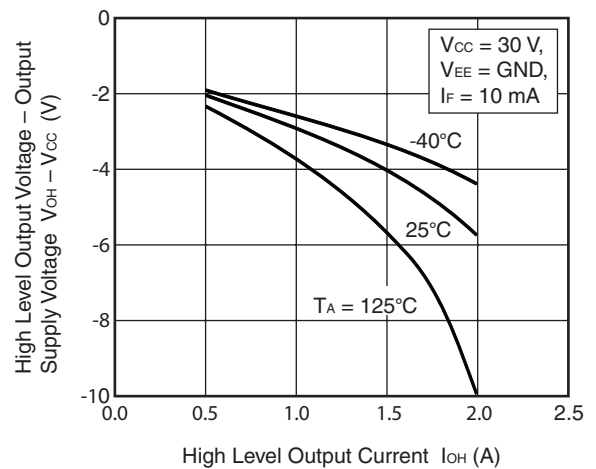
THRESHOLD INPUT CURRENT vs. AMBIENT TEMPERATURE



OUTPUT VOLTAGE vs. FORWARD CURRENT



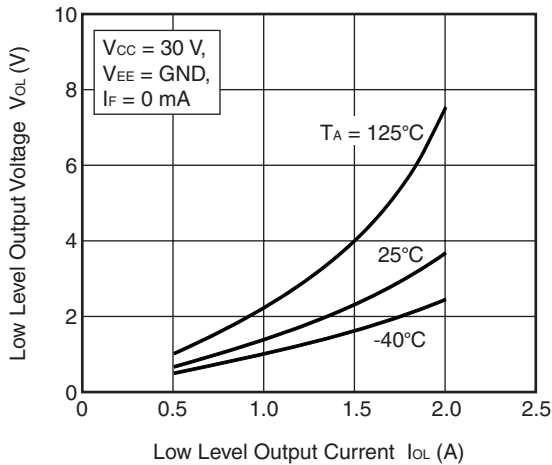
HIGH LEVEL OUTPUT VOLTAGE – OUTPUT SUPPLY VOLTAGE vs. HIGH LEVEL OUTPUT CURRENT



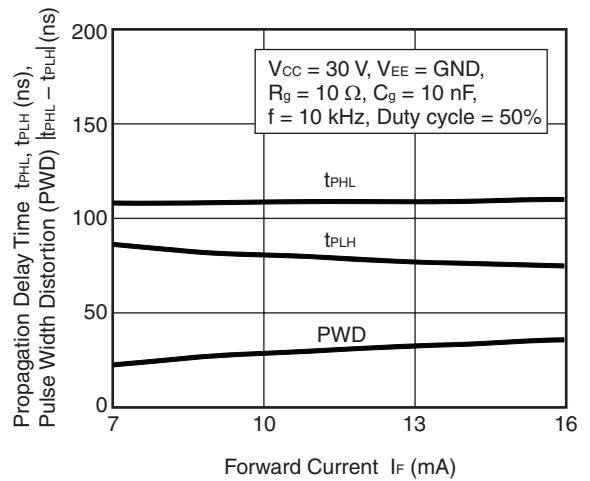
**Remark** The graphs indicate nominal characteristics.



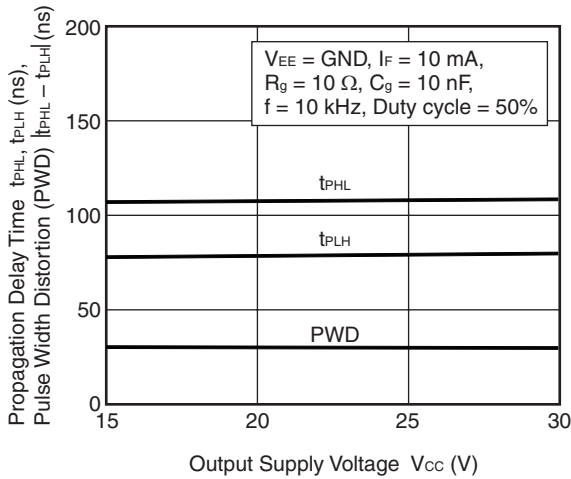
LOW LEVEL OUTPUT VOLTAGE vs. LOW LEVEL OUTPUT CURRENT



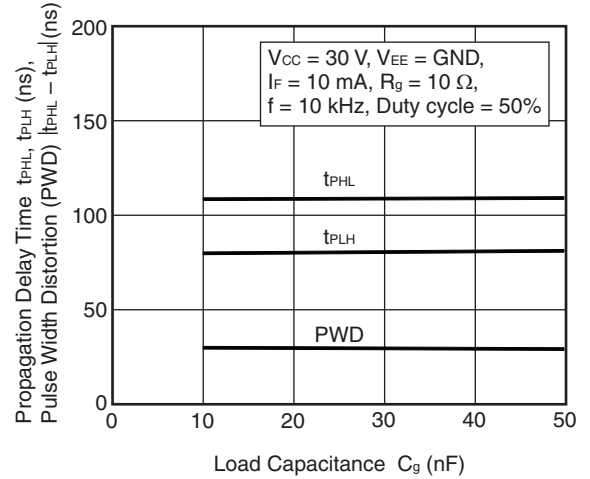
PROPAGATION DELAY TIME, PULSE WIDTH DISTORTION vs. FORWARD CURRENT



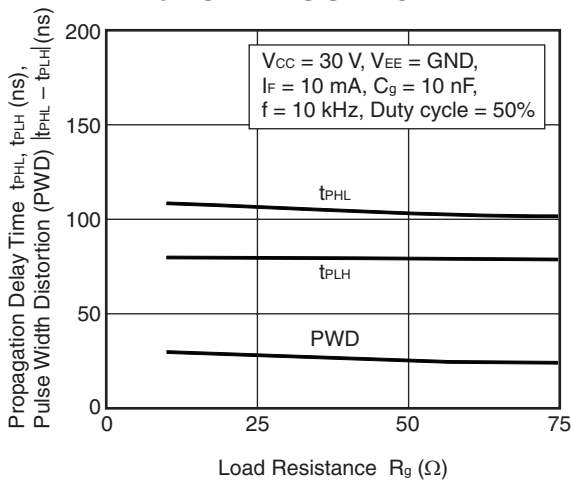
PROPAGATION DELAY TIME, PULSE WIDTH DISTORTION vs. OUTPUT SUPPLY VOLTAGE



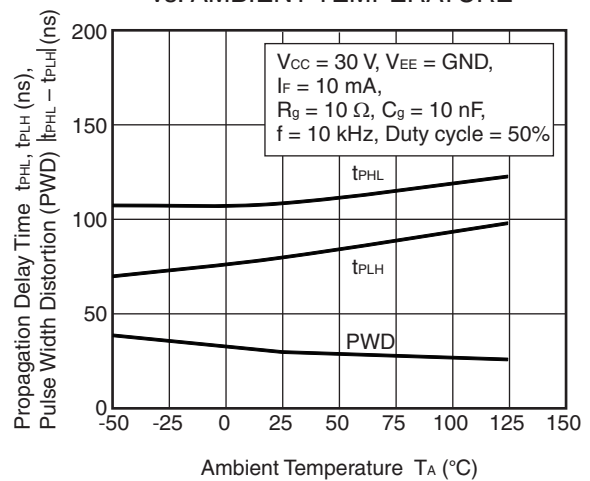
PROPAGATION DELAY TIME, PULSE WIDTH DISTORTION vs. LOAD CAPACITANCE



PROPAGATION DELAY TIME, PULSE WIDTH DISTORTION vs. LOAD RESISTANCE

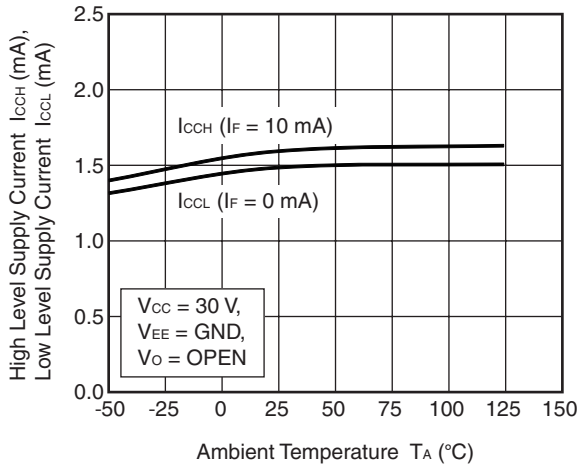


PROPAGATION DELAY TIME, PULSE WIDTH DISTORTION vs. AMBIENT TEMPERATURE

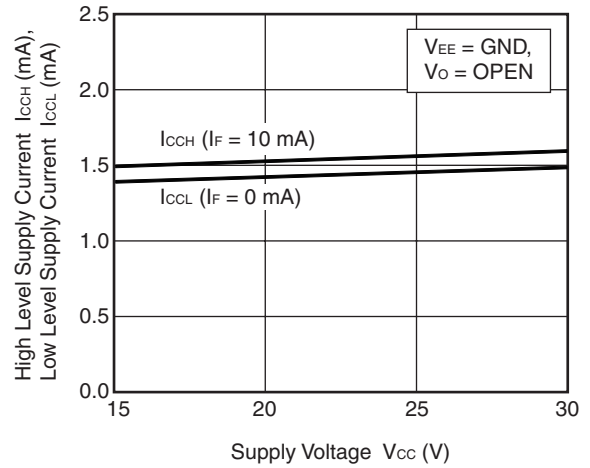


**Remark** The graphs indicate nominal characteristics.

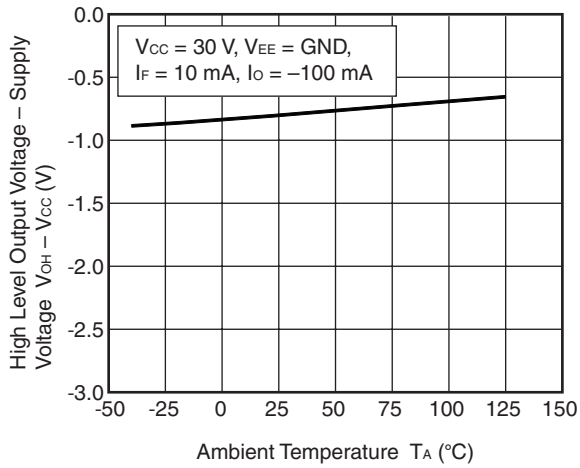
SUPPLY CURRENT vs. AMBIENT TEMPERATURE



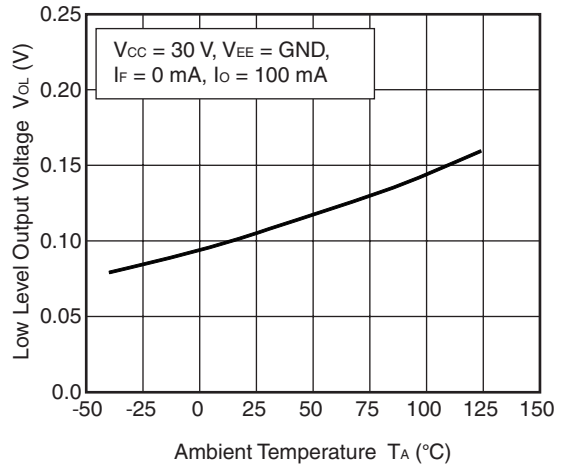
SUPPLY CURRENT vs. SUPPLY VOLTAGE



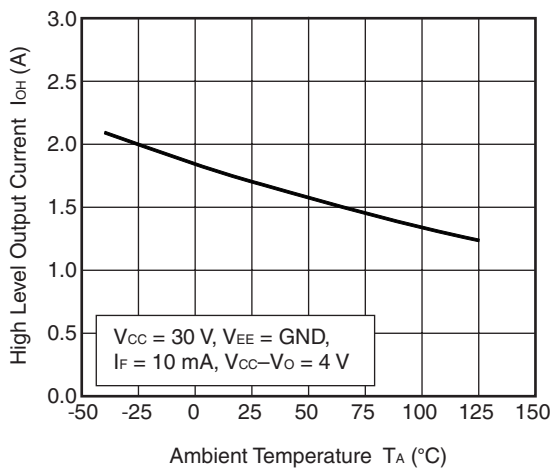
HIGH LEVEL OUTPUT VOLTAGE – SUPPLY VOLTAGE vs. AMBIENT TEMPERATURE



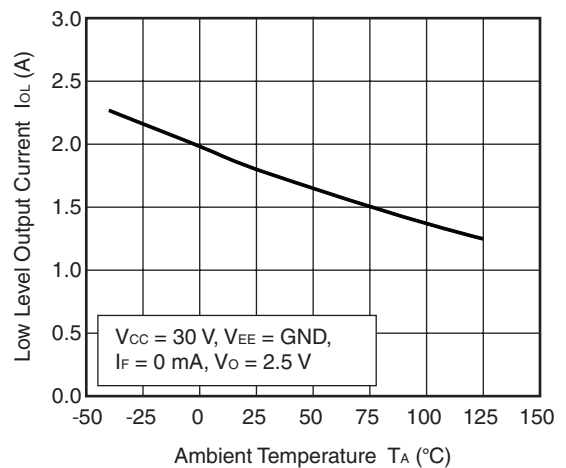
LOW LEVEL OUTPUT VOLTAGE vs. AMBIENT TEMPERATURE



HIGH LEVEL OUTPUT CURRENT vs. AMBIENT TEMPERATURE

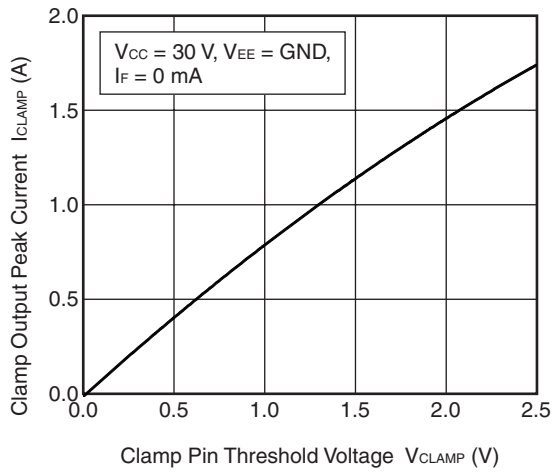


LOW LEVEL OUTPUT CURRENT vs. AMBIENT TEMPERATURE

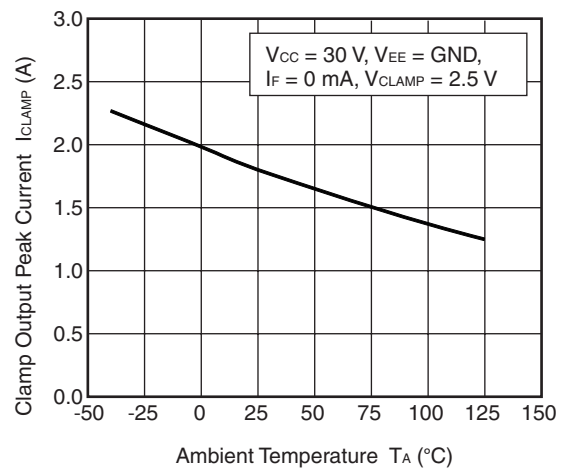


**Remark** The graphs indicate nominal characteristics.

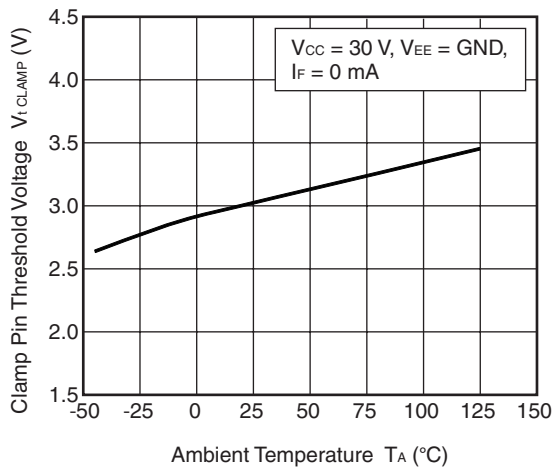
CLAMP OUTPUT PEAK CURRENT vs. CLAMP PIN THRESHOLD VOLTAGE



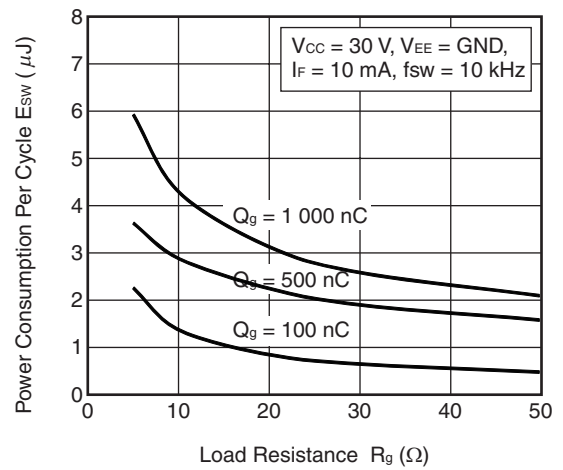
CLAMP OUTPUT PEAK CURRENT vs. AMBIENT TEMPERATURE



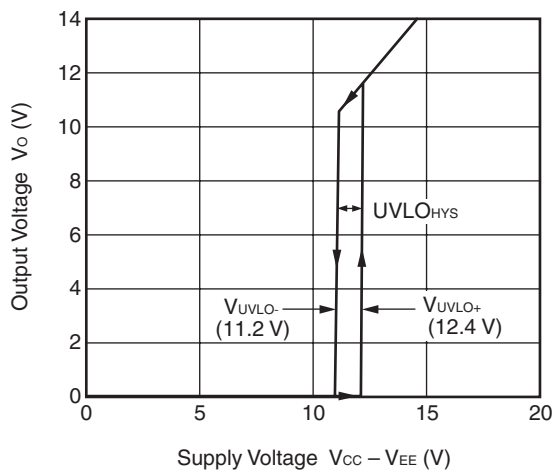
CLAMP PIN THRESHOLD VOLTAGE vs. AMBIENT TEMPERATURE



POWER CONSUMPTION PER CYCLE vs. LOAD RESISTANCE



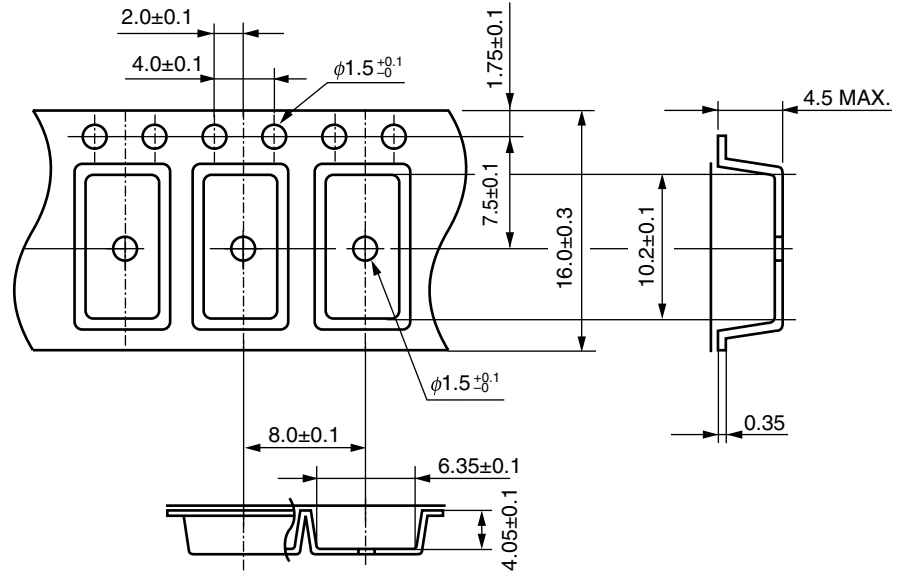
OUTPUT VOLTAGE vs. SUPPLY VOLTAGE



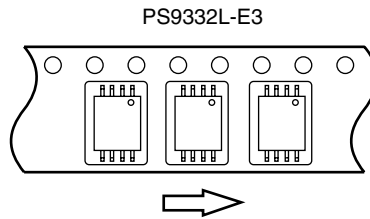
**Remark** The graphs indicate nominal characteristics.

**TAPING SPECIFICATIONS (UNIT: mm)**

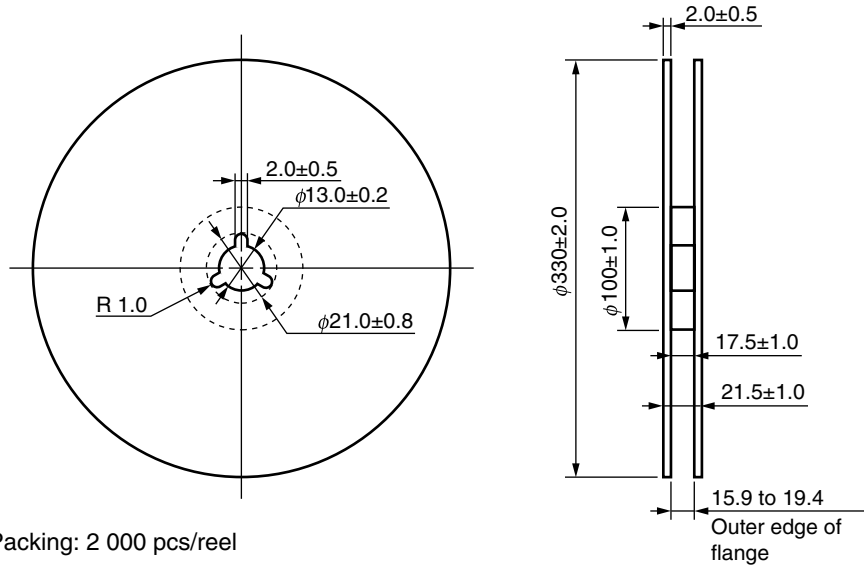
Outline and Dimensions (Tape)



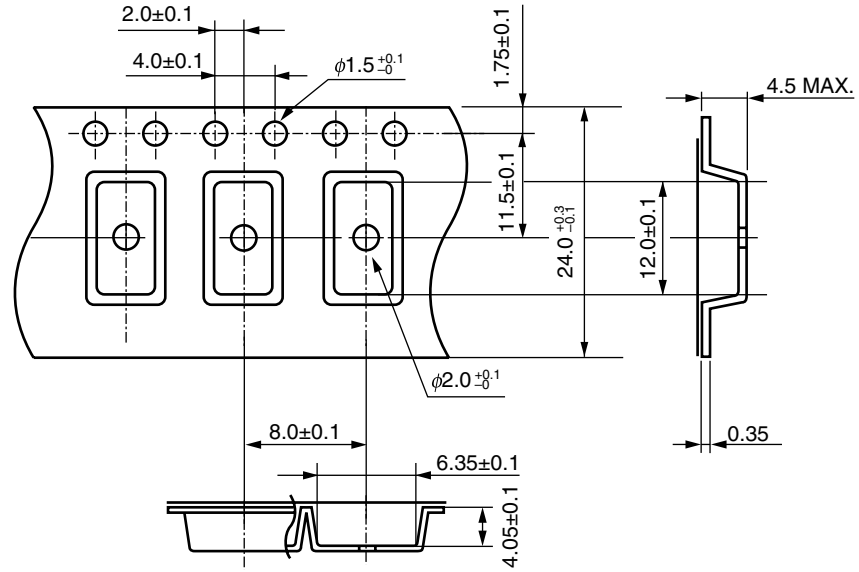
Tape Direction



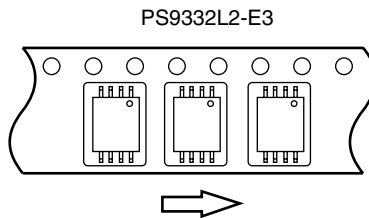
Outline and Dimensions (Reel)



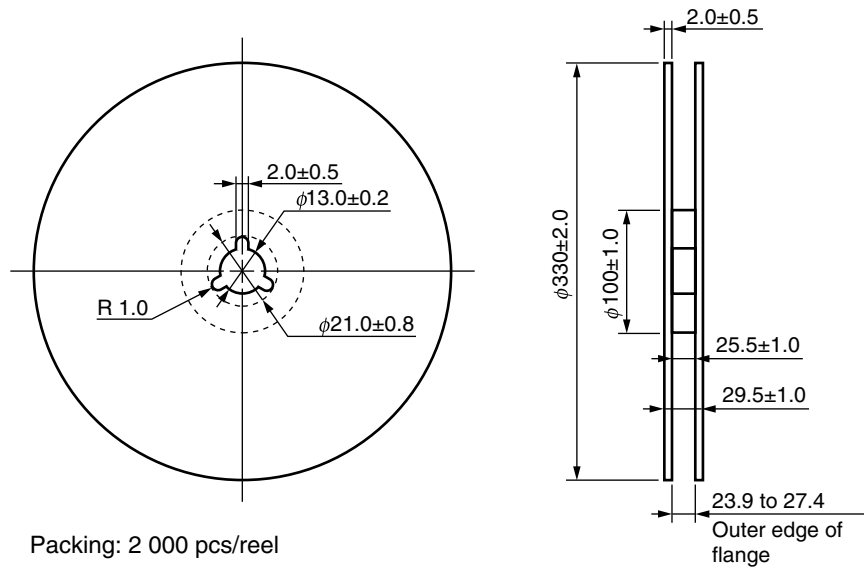
Outline and Dimensions (Tape)



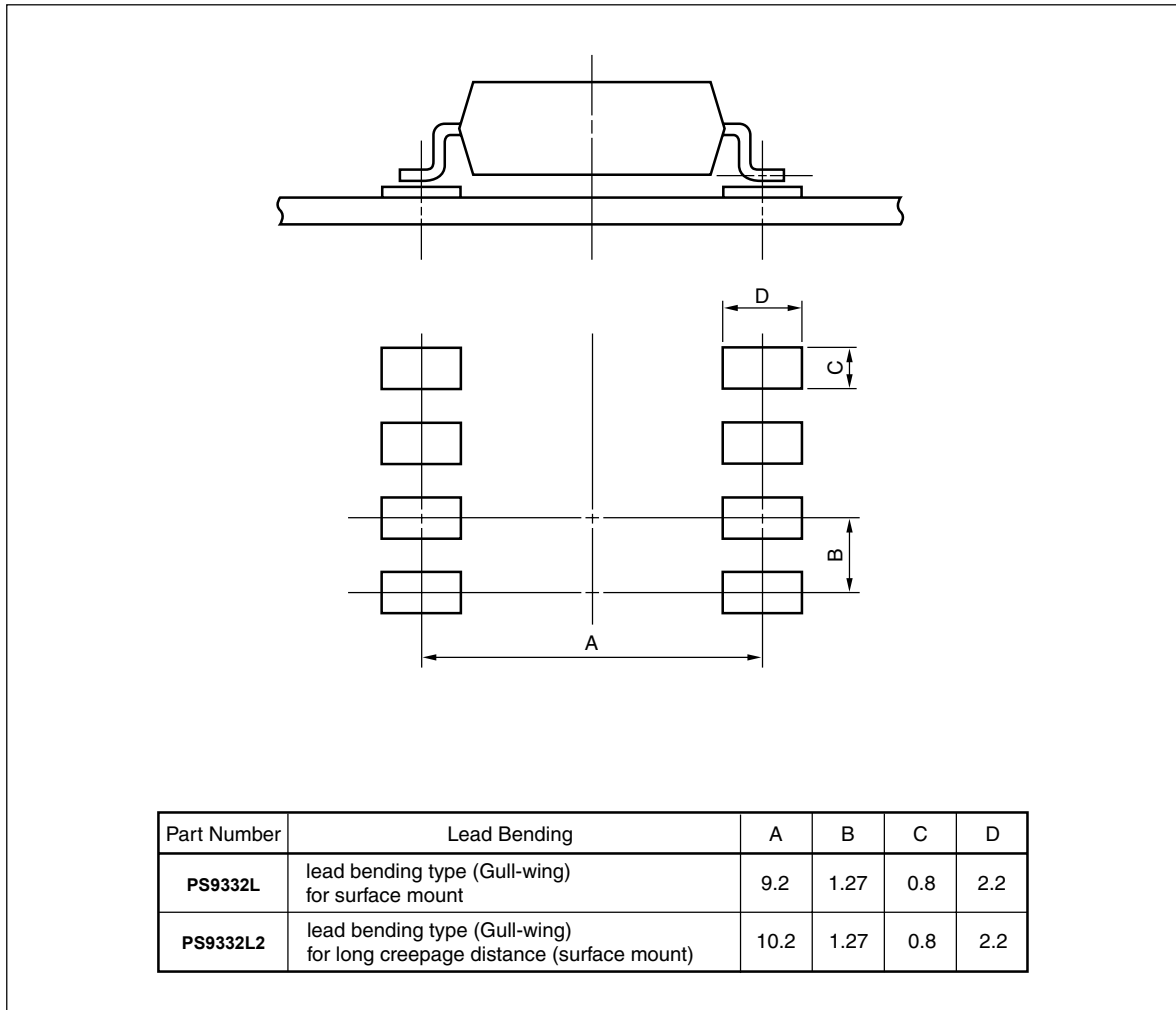
Tape Direction



Outline and Dimensions (Reel)



**RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)**



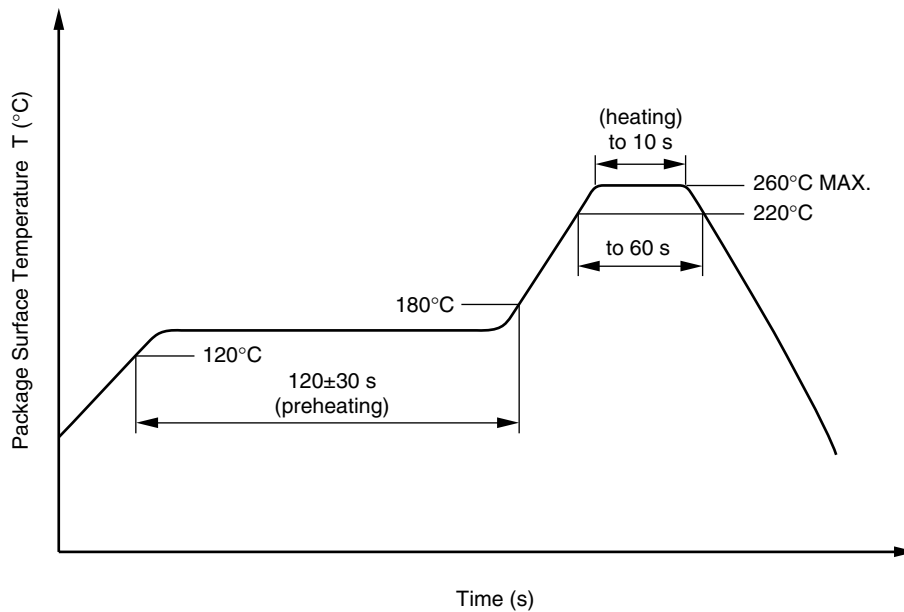
## NOTES ON HANDLING

### 1. Recommended soldering conditions

#### (1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120 ± 30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



#### (2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### (3) Soldering by Soldering Iron

- Peak Temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

#### (4) Cautions

- Fluxes Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

## 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

## USAGE CAUTIONS

1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. Board designing
  - (1) By-pass capacitor of more than 1.0  $\mu\text{F}$  is used between  $V_{CC}$  and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
  - (2) When designing the printed wiring board, ensure that the pattern of the IGBT collectors/emitters is not too close to the input block pattern of the photocoupler.

If the pattern is too close to the input block and coupling occurs, a sudden fluctuation in the voltage on the IGBT output side might affect the photocoupler's LED input, leading to malfunction or degradation of characteristics. (If the pattern needs to be close to the input block, to prevent the LED from lighting during the off state due to the abovementioned coupling, design the input-side circuit so that the bias of the LED is reversed, within the range of the recommended operating conditions, and be sure to thoroughly evaluate operation.)
  - (3) Pin 2,4 (which is an NC<sup>\*1</sup> pin) can either be connected directly to the GND pin on the LED side or left open. Unconnected pins should not be used as a bypass for signals or for any other similar purpose because this may degrade the internal noise environment of the device.

Note: \*1. NC: Non-Connection (No Connection).
3. Make sure the rise/fall time of the forward current is 0.5  $\mu\text{s}$  or less.
4. In order to avoid malfunctions, make sure the rise/fall slope of the supply voltage is 3 V/ $\mu\text{s}$  or less.
5. Avoid storage at a high temperature and high humidity.



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Parameter	Symbol	Spec.	Unit
Maximum repetitive peak operating isolation voltage	$U_{IORM}$	1 130	$V_{peak}$
Partial discharge test voltage at 100% production test $U_{pr} = 1.875 \times U_{IORM.}$ , Method b, $t_m=1sec$ , $p_d < 5 pC$	$U_{pr}$	1 808	$V_{peak}$
Partial discharge test voltage at Type test and Sample test $U_{pr} = 1.875 \times U_{IORM.}$ , Method a, $t_m=10sec$ , $p_d < 5 pC$	$U_{pr}$	2 119	$V_{peak}$
Maximum transient isolation voltage (Transient overvoltage $t_{ini}=60sec$ )	$U_{IOTM}$	8 000	$V_{peak}$
Installation classification (IEC 60664/ DIN EN 60664-1/ VDE0110 Part 1) for rated mains voltage $\leq 300$ Vr.m.s. for rated mains voltage $\leq 600$ Vr.m.s. for rated mains voltage $\leq 1\ 000$ Vr.m.s.		I - IV I - IV I - III	
Comparative tracking index (IEC 60112/ DIN EN 60112/ VDE 0303 Part 11)	CTI	175	
Material group (DIN EN 60664-1/ VDE0110 Part 1)		III a	
Pollution degree (DIN EN 60664-1/ VDE0110 Part 1)		2	
Climatic category (IEC 60068-1/ DIN EN 60068-1)		40/125/21	
Operating temperature range	$T_A$	-40 to +125	$^{\circ}C$
Storage temperature range	$T_{stg}$	-55 to +150	$^{\circ}C$
Isolation resistance, minimum value $V_{IO} = 500$ Vdc at $T_A = 25^{\circ}C$ $V_{IO} = 500$ Vdc at $T_A$ MAX. at least $100^{\circ}C$	Ris MIN. Ris MIN.	$10^{12}$ $10^{11}$	$\Omega$ $\Omega$
Safety limiting values ratings (maximum allowable in the event of a fault or a failure, see thermal derating curve)			
Maximum ambient safety temperature	$T_s$	175	$^{\circ}C$
Maximum input current	$I_{si}$	400	mA
Maximum output power	$P_{so}$	700	mW
Isolation resistance at $V_{IO}= 500$ Vdc, $T_A=T_s$	Ris MIN.	$10^9$	$\Omega$

<b>Caution</b>	GaAs Products	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"><li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.<ol style="list-style-type: none"><li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li><li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li></ol></li><li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li><li>• Do not lick the product or in any way allow it to enter the mouth.</li></ul>
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**Revision History****PS9332L, PS9332L2 Data Sheet**

<b>Rev.</b>	<b>Date</b>	<b>Description</b>	
		<b>Page</b>	<b>Summary</b>
0.01	Nov 30, 2012	–	First edition issued
1.00	Sep 06, 2013	Throughout	“Preliminary Data Sheet” is changed to “Data Sheet.”
		p.1	Addition of Safety standards
		p.3	Addition of ORDERING INFORMATION
		p.4	Modification of ABSOLUTE MAXIMUM RATINGS
		p.5	Modification of ELECTRICAL / SWITCHING CHARACTERISTICS
		p.6 to 7	Modification of TEST CIRCUIT
		p.8 to 11	Addition of TYPICAL CHARACTERISTICS
		p.17	Addition of SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

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